

# IEEE Wireless and Microwave Technology Conference

**WAMICON 2018**

**April 9<sup>th</sup> and 10<sup>th</sup> 2018**

**Sheraton**

**Sand Key, Florida**



**Submission Deadline: Friday February 9, 2018**

The 19th annual IEEE Wireless and Microwave Technology Conference (WAMICON 2018) will be held in Clearwater, Florida on April 9<sup>th</sup> and 10<sup>th</sup> 2018. The conference will address up-to-date multidisciplinary research needs and interdisciplinary aspects of wireless and RF technology. The program includes both oral and poster presentations as well as tutorials and special sessions. Prospective authors are invited to submit original and high-quality work for presentation at WAMICON 2018 and publication in IEEE Xplore. Conference website is [www.wamicon.org](http://www.wamicon.org). **WAMICON welcomes and encourages strong participation from industry, academic and governmental groups interested in advancing wireless and microwave technology.**

## TOPICS OF INTEREST INCLUDE

The central theme of WAMICON2018 will be “**mm-Waves and Internet of Things (IoT) for Commercial and Defense**”. We welcome submissions on all aspects of mm-wave and IoT related technologies including antennas, passive and active circuits, communication theory, and system concepts.

### **mm-Wave and Internet of Things (IoT)**

*5G Communications, MIMO and massive MIMO, beamforming, Machine-to-Machine (M2M) wireless, Internet of Space, Ultra-Wideband (UWB), Multi-Carrier, Spread Spectrum, Channel Characterization and Modeling, Cognitive Radios and Software Defined Radios*

### **Power Amplifiers**

*High-Efficiency PAs, Linearization and Efficiency Enhancement Techniques and Topologies, Novel PA Architectures, High-Power Devices, Linear and Nonlinear Device Modeling and CAD, Thermal Considerations and Reliabilities, PA Applications*

### **Active Components and Systems**

*Transceiver Design, Multi-Band RF Circuits and Systems, System-On-Chip, System-In-Package, Low-Power IC, Low-Noise IC, Radar RF/MMIC Electronics, Terahertz Electronics, Active (Non-Foster) Filters and Non-Foster Impedance Matching*

### **Passive Components and Antennas**

*Filters, Transmission Line Components, MEMS, Advanced Packaging, Antennas and Arrays, Meta-Materials, Frequency Selective Surface, Non-Foster Impedance Matching*

### **Microwave Applications**

*Biomedical Applications, Wireless Sensing, Energy Harvesting, Wireless Power Transfer, Radar, Additive Manufacturing*

## PAPER SUBMISSION INSTRUCTIONS

Authors are asked to submit papers electronically in .PDF format. In order to be considered for publication by the Technical Program Committee, a submission of 3-4 pages, clearly describing the concept and results must be submitted before the deadline of February 9, 2018. The conference webpage at [www.wamicon.org](http://www.wamicon.org) has complete details of submission requirements. Submissions will be evaluated for originality, significance of the work, technical soundness, and interest to a wide audience.

### **General Chair**

Ryan Baker – Wolfspeed, A Cree Company  
[Ryan.Baker@Wolfspeed.com](mailto:Ryan.Baker@Wolfspeed.com)

### **General Vice-Chair**

Jessica Coots – Harris  
[jcoots01@harris.com](mailto:jcoots01@harris.com)

### **Technical Program Chairs**

HjalTI Sigmarrsson – U of Oklahoma  
[h.sigmarrsson@ou.edu](mailto:h.sigmarrsson@ou.edu)

Kelvin Yuk – Echoic Engineering  
[ksyuk@echoicrf.com](mailto:ksyuk@echoicrf.com)

### **Invited Papers Chair**

TBD

### **Poster Session Chair**

Serita Cronin – Tampa Microwave  
[serita@tampabay.rr.com](mailto:serita@tampabay.rr.com)

### **Local Arrangements Chairs**

Larry Dunleavy – Modelithics  
[ldunleavy@modelithics.com](mailto:ldunleavy@modelithics.com)

Jim Culver – Raytheon  
[jwculver@ieee.org](mailto:jwculver@ieee.org)

### **Exhibits & Sponsorship Chairs**

Jim Assurian – Reactel  
[jassurian@reactel.com](mailto:jassurian@reactel.com)

Laura Levesque – Modelithics  
[llevsque@modelithics.com](mailto:llevsque@modelithics.com)

### **Publicity Chair**

Michael Hallman – Microwave Journal  
[mhallman@mwjournal.com](mailto:mhallman@mwjournal.com)

### **Publications Chair**

Gary Breed - AY Technologies  
[gary@aytechnologies.com](mailto:gary@aytechnologies.com)

### **Registration Chair**

Craig Sapashe – Keysight Technologies  
[craig\\_sapashe@keysight.com](mailto:craig_sapashe@keysight.com)

### **Finance Chair**

Holly Dunleavy – Modelithics  
[hdunleavy@modelithics.com](mailto:hdunleavy@modelithics.com)

### **Student Volunteers**

Xun Gong – Univ. Central Florida  
[Xun.Gong@ucf.edu](mailto:Xun.Gong@ucf.edu)

### **Henning Award Chair**

Tom Weller – Univ. So. Florida  
[weller@usf.edu](mailto:weller@usf.edu)

### **Local Industry Liaison**

TBD

### **IEEE YP Liaison**

Michael Grady – U of South Florida  
[Grady.michael.d@gmail.com](mailto:Grady.michael.d@gmail.com)

### **WAMICON EXCOM Chair**

Jim Culver - Raytheon  
[jwculver@ieee.org](mailto:jwculver@ieee.org)

### **IEEE Liaison**

Larry Dunleavy - Modelithics  
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**Papers Due: Fri., Feb. 9, 2018**  
**Author Notification: Fri., Feb. 23, 2018**  
**Final Papers Due: Fri., Mar. 2, 2018**